

| Ref # | Hits | Search Query  | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|------|---|---|------------------|---------|------------------|
| L1    | 431  | intel.as. and wire and (die ic chip) same (contact pad) | USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB              | OR               | ON      | 2005/10/31 09:24 |
| L2    | 1183 | 257/786 and wire same (die ic chip) same (contact pad)  | USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB              | OR               | ON      | 2005/10/31 09:27 |
| L3    | 1322 | 257/786 and wire same (die ic chip) same (contact pad)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/10/31 09:27 |
| L4    | 1191 | 257/786 and wire with (die ic chip) same (contact pad)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/10/31 09:27 |
| L5    | 1110 | 257/786 and wire with (die ic chip) with (contact pad)  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/10/31 09:28 |